

40-44GHz Up converter

GaAs Monolithic Microwave IC

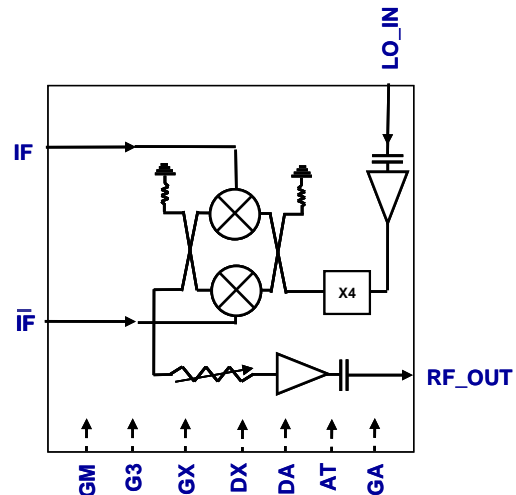
Description

The CHU2299-99F is an up converter multifunction chip, which integrates LO X4 multiplier, a balanced cold FET mixer and a RF amplifier with gain control.

It is designed for a wide range of applications, from military to commercial communication systems.

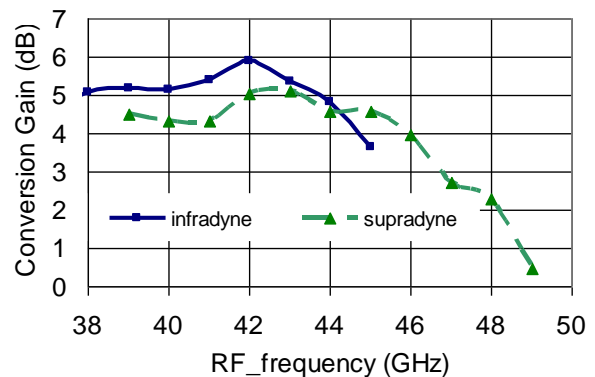
The circuit is manufactured with a power pHEMT process, 0.15 μ m gate length, via holes through the substrate, air bridges and electron beam gate lithography.

It is available in chip form.



Main Features

- 40-44GHz RF bandwidth
- 5dB conversion gain
- 20dB of gain control
- x4 LO frequency multiplier
- 16dBm output IP3
- DC bias: Vd = 4V @ Id = 250mA
- Chip size 3.97x2.25x0.1mm



Main Characteristics

Tamb.= +25°C

Symbol	Parameter	Min	Typ	Max	Unit
F _{RF}	RF frequency range	40		44	GHz
F _{LO}	LO frequency range	9.5		11.5	GHz
G _c	Conversion gain		5		dB

Electrical Characteristics

Tamb.= +25°C

Symbol	Parameter	Min	Typ	Max	Unit
F _{RF}	RF frequency range	40		44	GHz
F _{LO}	LO frequency range	9.5		11.5	GHz
G _c	Conversion gain @min. attenuation		5		dB
ΔG	Gain control range		20		dB
P _{LO}	LO Input power		1		dBm
NF	Noise figure at gain max Noise figure all case		13 27		dB
OIP3	Output IP3@ min. attenuation Output IP3@ max. attenuation		16 4		dBm
RL	RF & LO Return Loss		12		dB
4xF _{LO_1k}	4xLO leakage on RF port @min. Att.		-5		dBm
DX, DA	LO multiplier, buffer and RF amplifier biasing		4		V
GM	Mixer DC gate biasing		-0.6		V
G3	LO buffer gate biasing		-0.3		V
GX	Multiplier gate biasing		-1.2		V
GA	RF amplifier gate biasing		-0.5		V
AT	Attenuation voltage control	-1.5		0.5	V
I _d	Drain current		250		mA

Electrostatic discharge sensitive device observe handling precautions!

These values are representative of chip on board measurements with an external 180° hybrid balun between IF & IFb.

Absolute Maximum Ratings ⁽¹⁾

Tamb.= +25°C

Symbol	Parameter	Values	Unit
DX, DA	LO multiplier, buffer and RF amplifier biasing	4.5	V
I _d	Drain bias current	310	mA
G3, GA	Amplifier gate biasing	-2; +0.6	V
GX, GM	Multiplier and mixer gate biasing	-2; +0.6	V
AT	Attenuation voltage control	-2	V
P _{LO}	Maximum peak LO input power overdrive ⁽²⁾	10	dBm
Pin _{RF}	Maximum peak RF input power overdrive ⁽²⁾	17	dBm
T _j	Junction temperature	175	°C
T _a	Operating temperature range	-40 to +85	°C
T _{stg}	Storage temperature range	-55 to +155	°C
R _{Th}	Thermal resistance, Tback side = +85°C, Ptotal = 1 W	73	°C/W

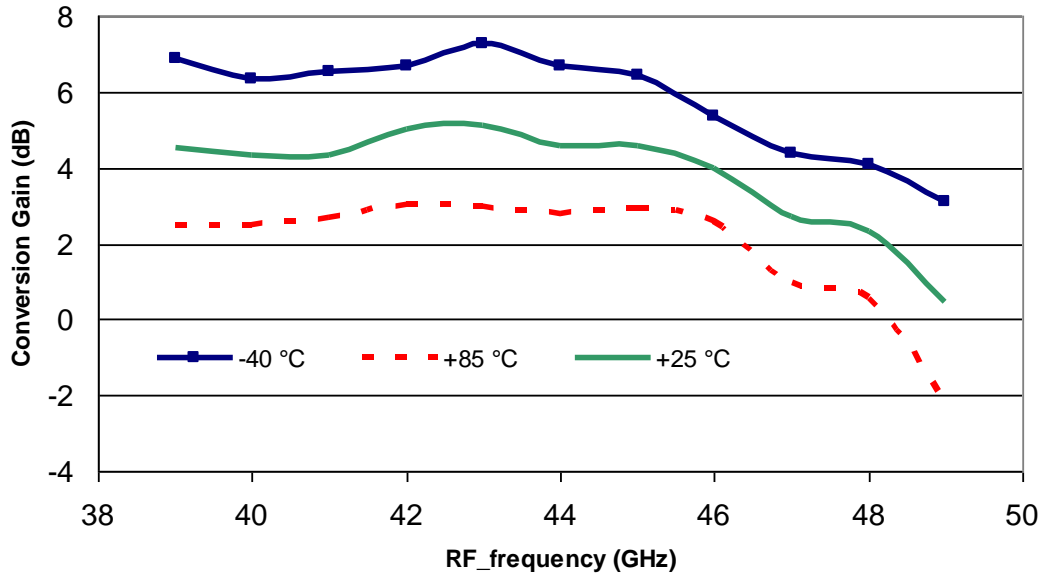
⁽¹⁾ Operation of this device above anyone of these parameters may cause permanent damage

⁽²⁾ Duration < 1s

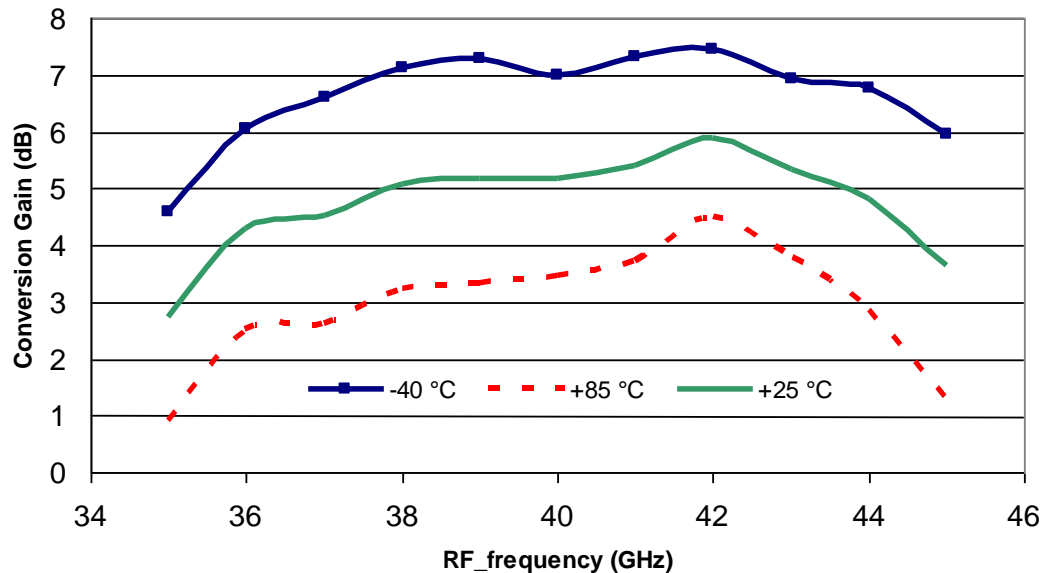
Typical chip on board Measurements in Temperature

DX = DA = 4V, GA = -0.5V, GM = -0.6V, G3 = -0.3V, GX = -1.2V, P_LO = 1dBm.
 These values are representative of onboard measurements as defined on the paragraph "Evaluation mother board". The losses are de-embedded.

Conversion Gain versus RF frequency & temperature
 RF= 4LO+IF; IF = 2GHz; AT = -1.5V



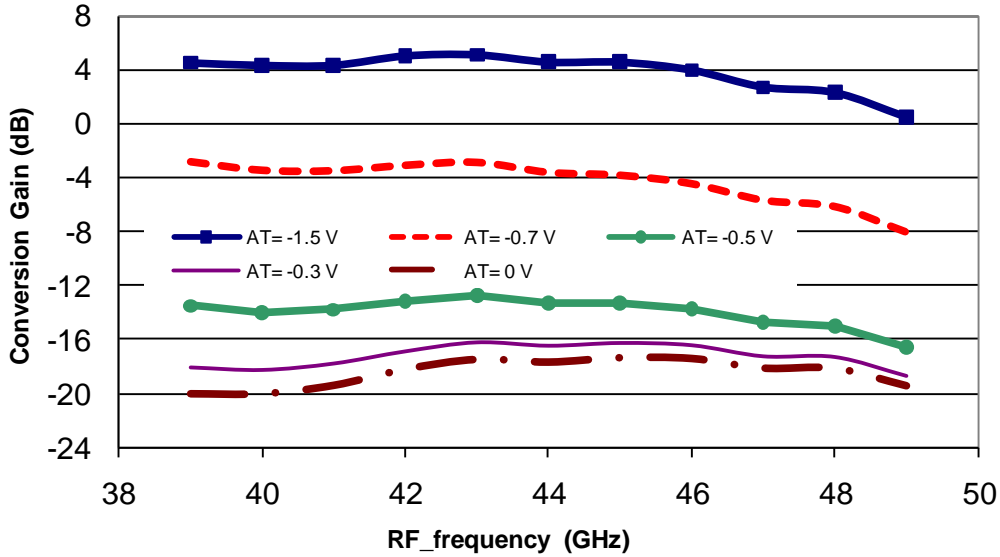
Conversion Gain versus RF frequency & temperature
 RF= 4LO-IF; IF = 2GHz; AT = -1.5V



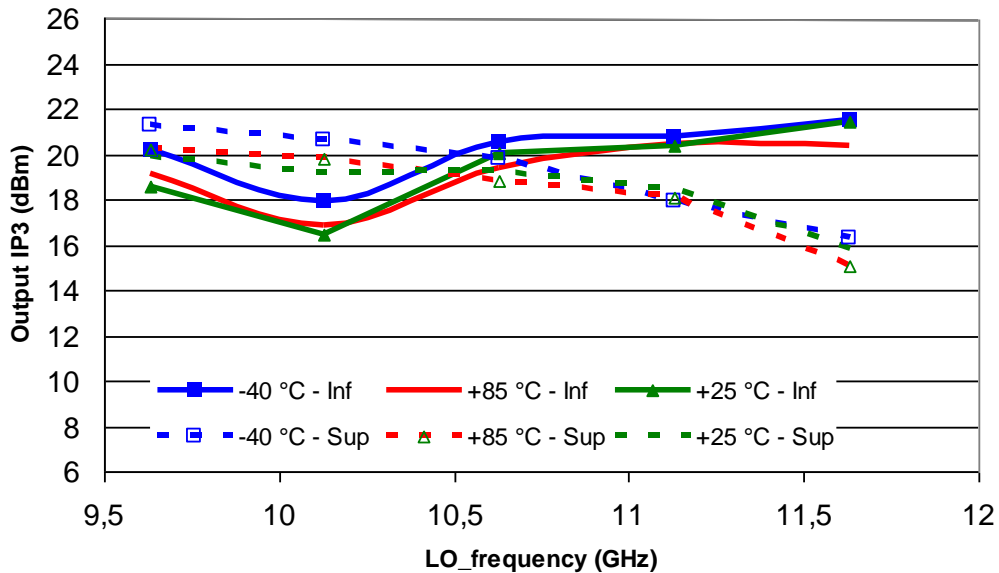
Typical chip on board Measurements in Temperature

DX = DA = 4V, GA = -0.5V, GM = -0.6V, G3 = -0.3V, GX = -1.2V, P_LO = 1dBm.

Conversion Gain versus RF frequency & attenuation
RF = 4LO+IF; IF = 2GHz

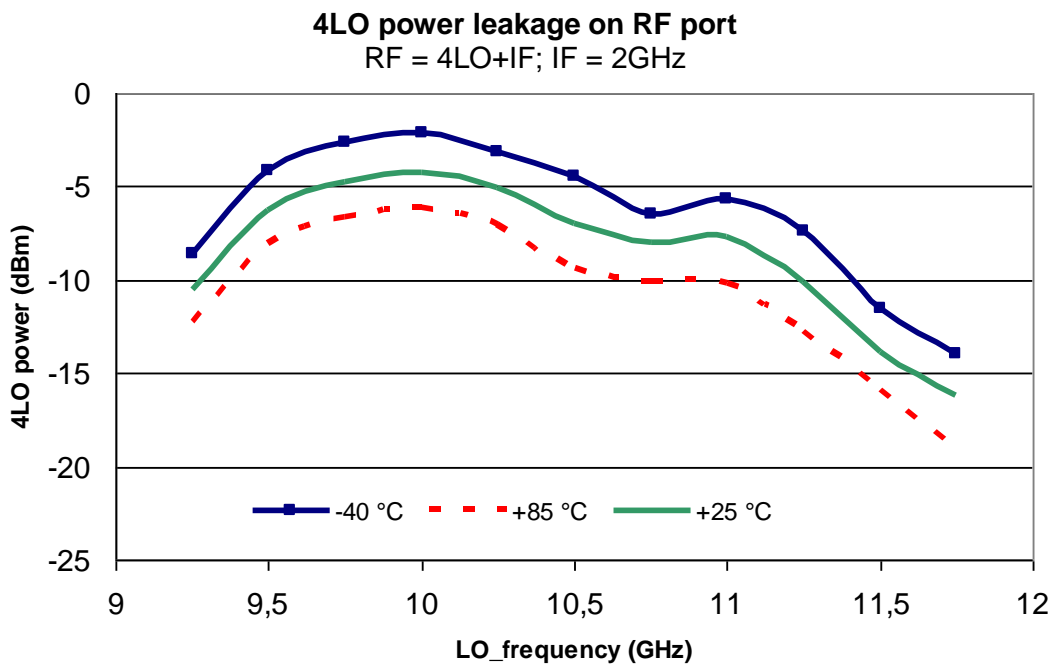
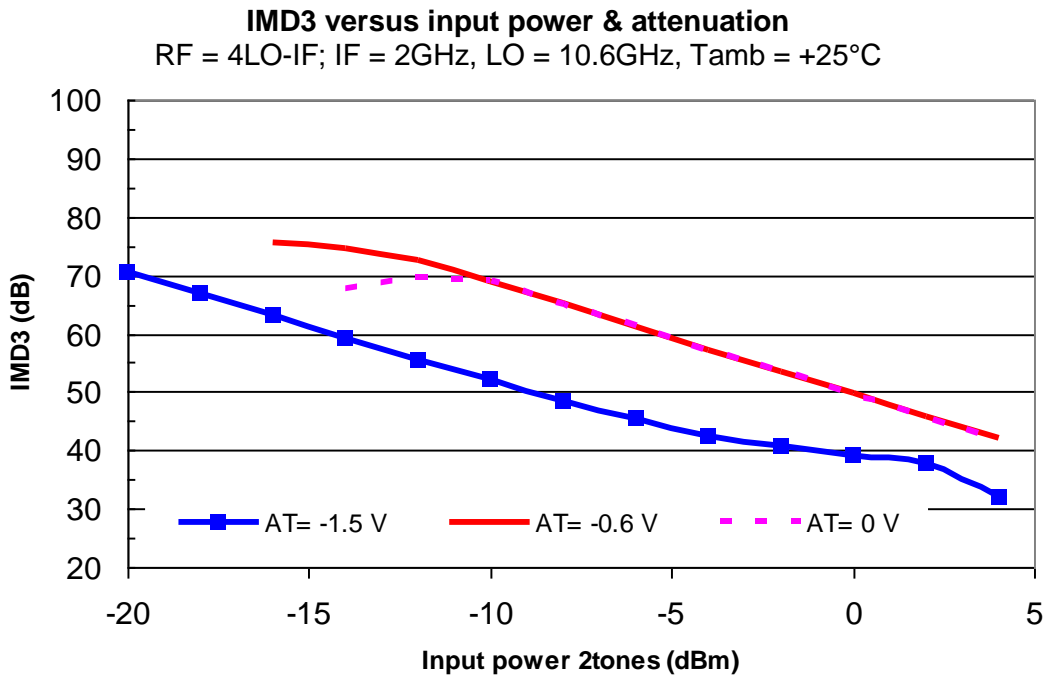


Output IP3 versus LO frequency at max. gain
RF = 4LO+/-IF; IF = 2GHz; Pin = -16dBm



Typical chip on board Measurements in Temperature

DX = DA = 4V, GA = -0.5V, GM = -0.6V, G3 = -0.3V, GX = -1.2V, P_LO = 1dBm.

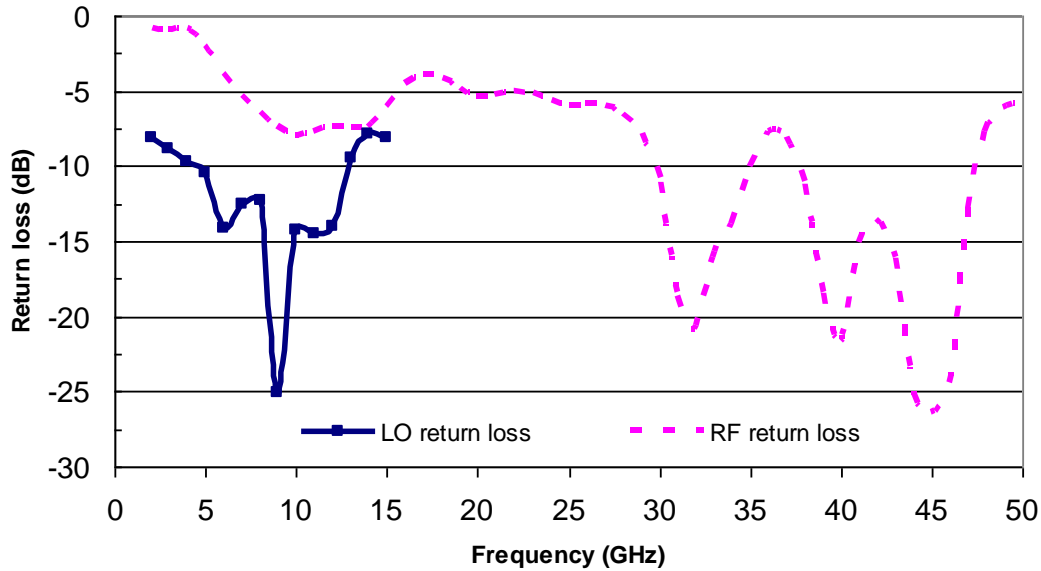


Typical chip on board Measurements

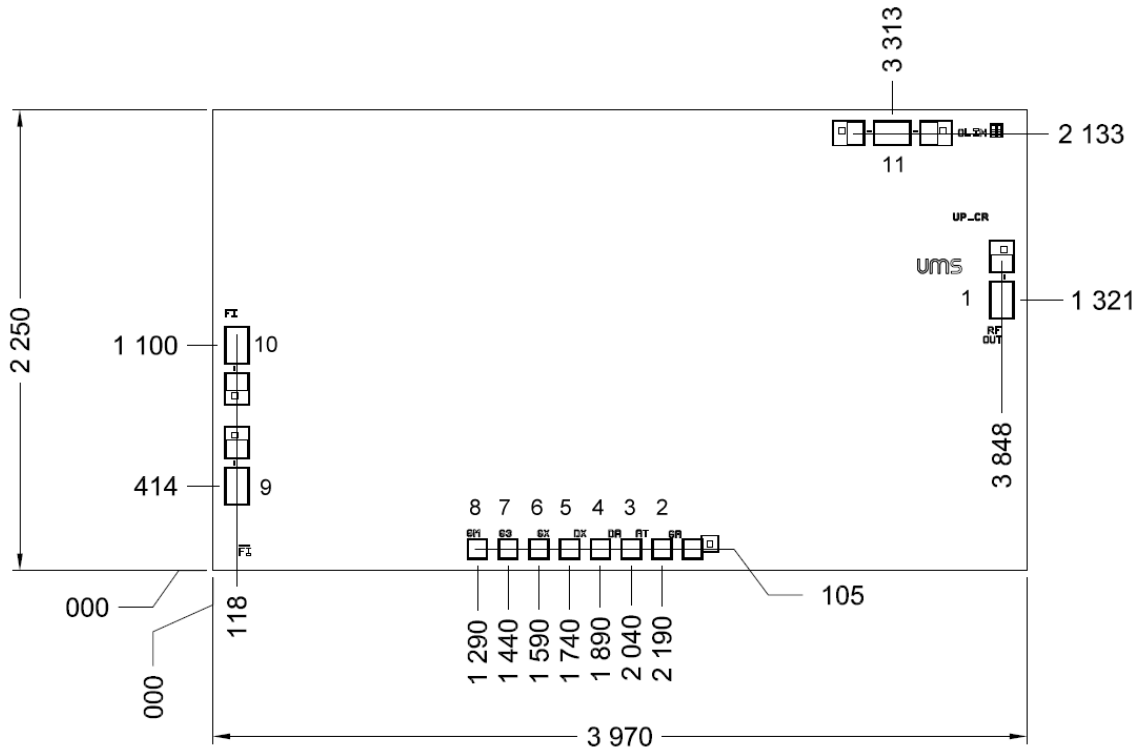
Tamb = +25°C, DX = DA = 4V, GA = -0.5V, GM = -0.6V, G3 = -0.3V, GX = -1.2V,
P_LO = 1dBm.

RF & LO return loss (in the connectors plan)

RF = 4LO-IF; IF = 2GHz, LO = 10.6GHz



Mechanical data



Chip thickness: 100 µm, units: µm, tol: +/- 35 µm

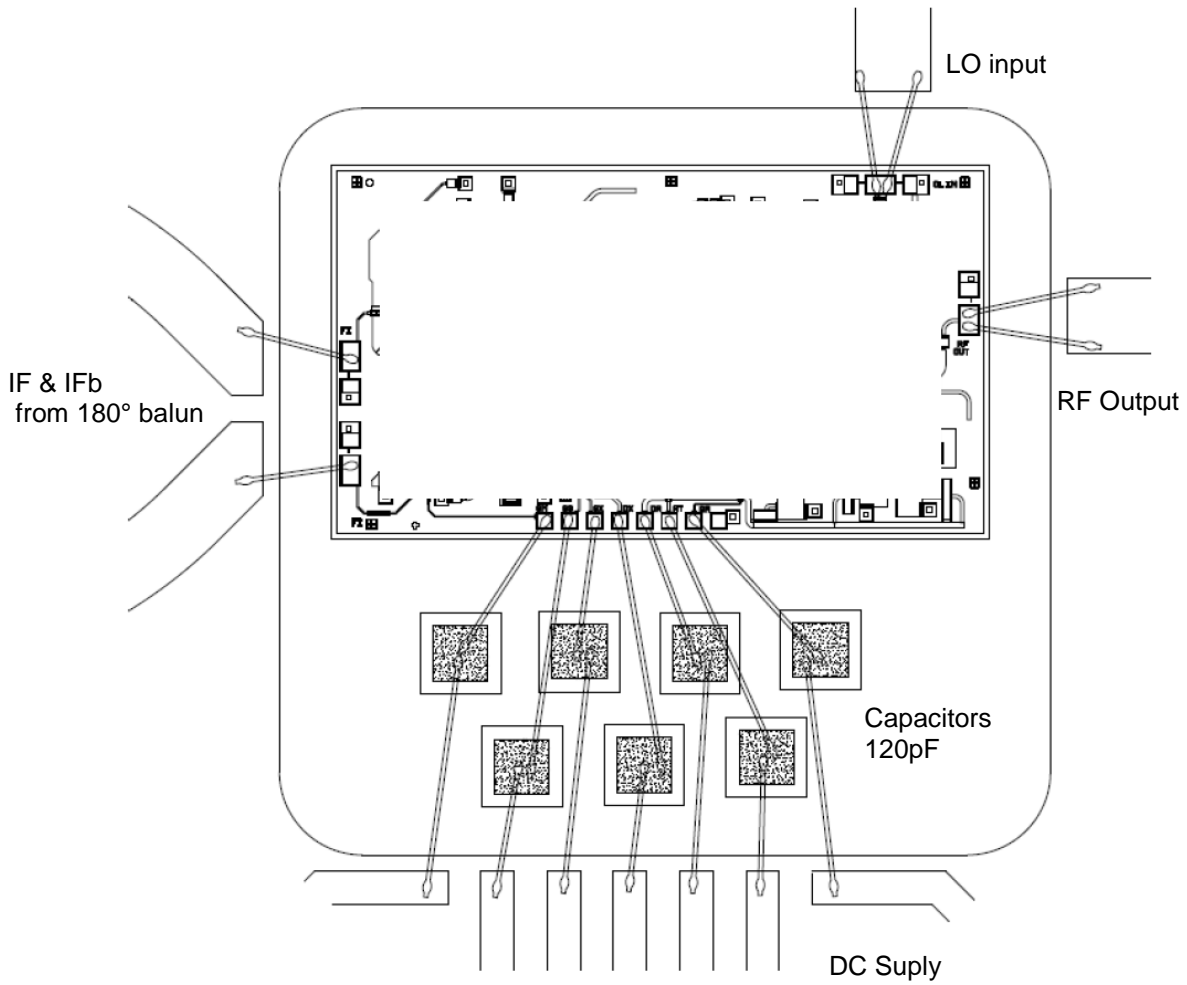
DC pads = 92x92 µm, RF pads = 178x114 µm

Pin number	Pin name	Description
1	RF_OUT	RF output
2	GA	RF buffer gate voltage
3	AT	Attenuation control voltage
4	DA	RF buffer drain voltage
5	DX	Multiplier & LO Buffer drain voltage
6	GX	Multiplier gate voltage
7	G3	Buffer gate voltage
8	GM	Mixer gate voltage
9, 10	IF & IFb	IF inputs
11	LO_IN	LO input

Recommended biasing

Pin Name	Pin Number	Parameter	Nominal value
GM	8	Mixer Gate voltage	-0.6V
G3	7	Buffer Gate voltage	-0.3V
GX	6	X4 Gate voltage	-1.2V
GA	2	RF amplifier Gate voltage	-0.5V
DX	5	X4 Drain voltage	4V
DA	4	RF amplifier Drain voltage	4V
AT	3	Attenuation control voltage	-1.5V to +0.5V

Chip assembly



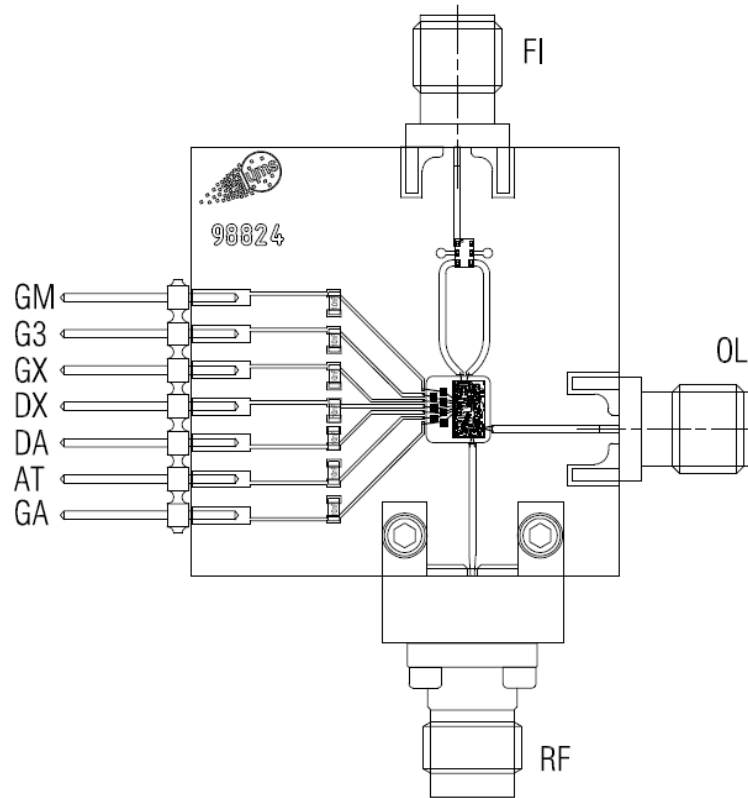
Note: Supply feed should be capacitively bypassed. 25 μ m diameter gold wire is recommended

Evaluation mother board

Based on typically Ro4003 / 8 mils or equivalent.

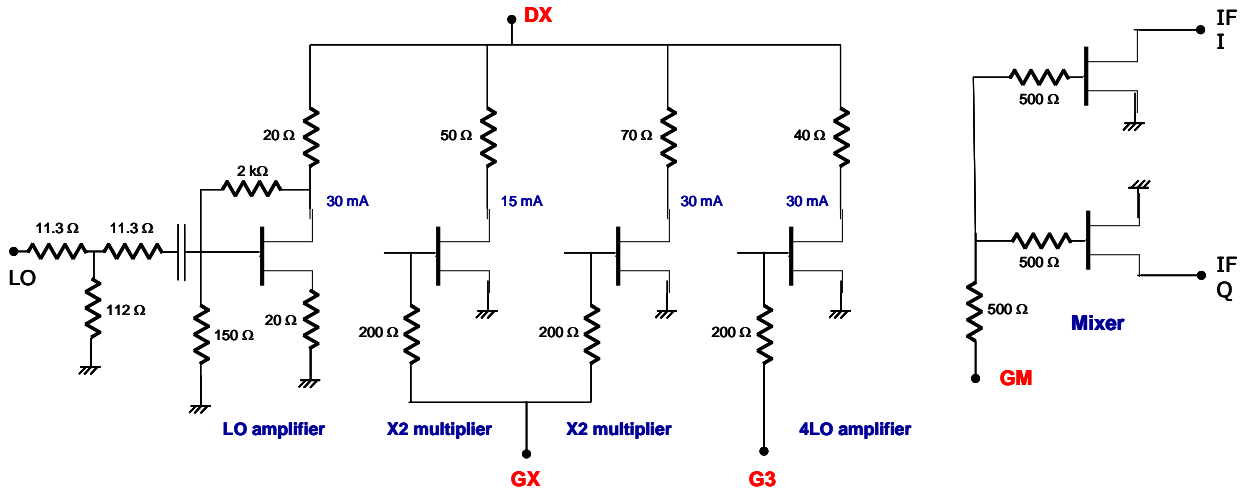
Decoupling capacitors of 10nF \pm 10% and chip 120pF \pm 10%

180° hybrid balun: 2-2.5GHz

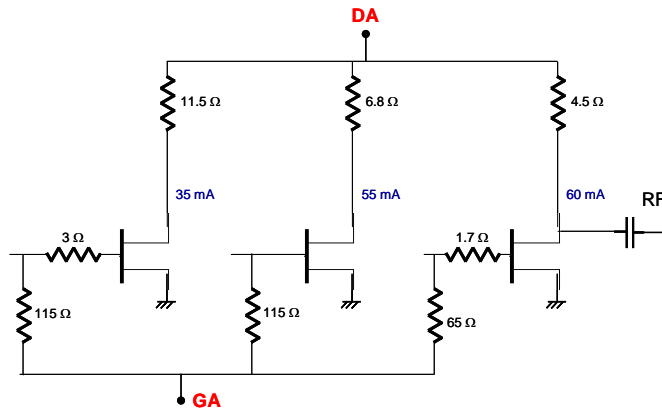


DC Schematic

LO multiplier and buffers: 4V, 105mA



RF amplifier: 4V, 150mA



Notes

Recommended ESD management

Refer to the application note AN0020 available at <http://www.ums-gaas.com> for ESD sensitivity and handling recommendations for the UMS products.

Recommended environmental management

UMS products are compliant with the regulation in particular with the directives RoHS N°2011/65 and REACH N°1907/2006. More environmental data are available in the application note AN0019 also available at <http://www.ums-gaas.com>.

Ordering Information

Chip form:

CHU2299-99F/00

Information furnished is believed to be accurate and reliable. However **United Monolithic Semiconductors S.A.S.** assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of **United Monolithic Semiconductors S.A.S.**. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. **United Monolithic Semiconductors S.A.S.** products are not authorised for use as critical components in life support devices or systems without express written approval from **United Monolithic Semiconductors S.A.S.**